



BITNG LAB UPDATE

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Date 2/25/2021

Outline

- Progress to date
- Path forward

PROGRESS TO DATE

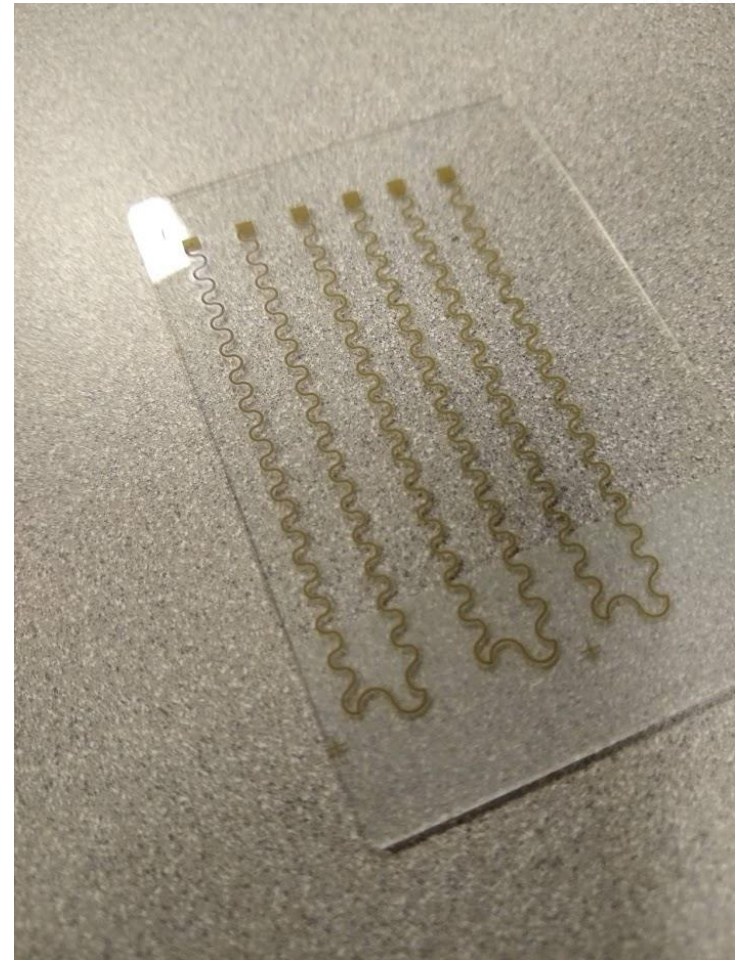
Progress from last week

- Shriner's project
 - Strain gauge
 - firmware

SHRINER'S PROJECT

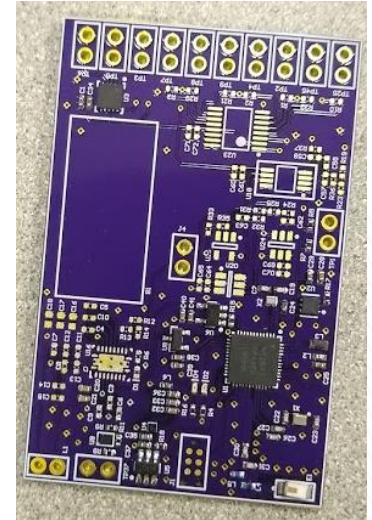
Strain Sensor: Round #7

- PDMA: Finished
- PI: Finished
- AG NW: Finished
- Conductivity Test: ~600 ohms
- ECO-FLEX: TO-DO
- ASSEMBLY: TO-DO
- ENCAPSULATION: TO-DO
- Characterization: TO-DO
- Conclusions
 - Less AgNW passes
 - (5 vertical passes to 3)
 - Wider/Thicker PI layers
- Next steps
 - Reduce AgNW width
 - (4 horizontal passes to 2)
 - Increase sensitivity
- Lab Session: Friday 3/05



Firmware Development

- Drivers complete
- Pressure Sensor:
 - ~~Testing with pressure sensor~~
 - ~~Fix function to change sampling rate~~
 - ~~Create document to detail app communication~~
 - Meet with Jihoon to encapsulate sensors
- Flex PCB:
 - Parts ordered from Digikey
 - PCBMinions order for Flex PCBs



PATH FORWARD

Path forward (2/22/21 – 3/01/21)

- Shriner's Project:
 - Literature review
 - Strain gauge, round #7
- Firmware development
 - ~~Pressure sensor~~
 - LP-ECG power consumption

APPENDIX